

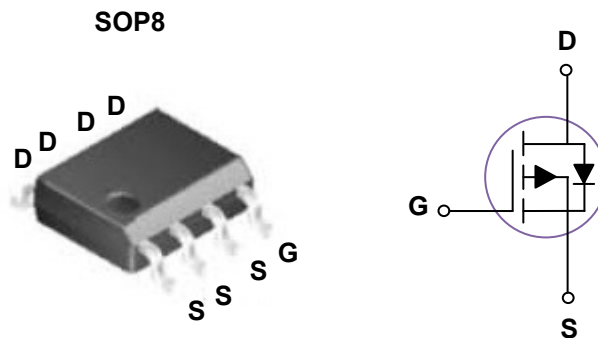
## P-Channel Enhancement Mode Power MOSFET

### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### Features

$V_{DS}$	-60V
$I_D$ (at $V_{GS}=-10V$ )	-6.2A
$R_{DS(ON)}$ (at $V_{GS}=-10V$ )	45mΩ(Max)
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$ )	60mΩ(Max)



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted					
Parameter		Symbol	Maximum	Units	
Drain-Source Voltage		$V_{DS}$	-60	V	
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V	
Drain Current-Continuous	TC=25°C	$I_D$	-6.2	A	
	TC=100°C	$I_D$	-4.5	A	
Drain Current – Pulsed		$I_{DM}$	-25	A	
Maximum Power Dissipation		$P_D$	2	W	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 To 150	°C	
Thermal Characteristics					
Parameter		Symbol	Typ	Max	Unit
Thermal Resistance junction-case		$R_{\theta Jc}$		1.1	°C /W
Thermal Resistance junction-to-Ambient		$R_{\theta JA}$		60	°C /W

**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-60			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-60V, V_{GS}=0V$			1	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0	-1.6	-2.2	V
$R_{DS(ON)}$	Drain-Source On-State esistance	$V_{GS}=-10V, I_D=-6.0A$		38	45	m $\Omega$
		$V_{GS}=-4.5V, I_D=-5.0A$		50	60	m $\Omega$
<b>DYNAMIC PARAMETERS</b>						
$C_{ISS}$	Input Capacitance	$V_{DS}=-30V, V_{GS}=0V,$ $F=1.0MHz$		2400		pF
$C_{OSS}$	Output Capacitance			175		pF
$C_{RSS}$	Reverse Transfer Capacitance			110		pF
<b>SWITCHING PARAMETERS</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=-30V, I_D=-1A,$ $V_{GS}=-10V,$ $R_G=3\Omega$		9.8		nS
$t_r$	Turn-on Rise Time			6.0		nS
$t_{d(off)}$	Turn-Off Delay Time			44		nS
$t_f$	Turn-Off Fall Time			12		nS
$Q_g$	Total Gate Charge	$V_{DS}=-30V, I_D=-5A,$ $V_{GS}=-4.5V$		22		nC
$Q_{gs}$	Gate-Source Charge			9.0		nC
$Q_{gd}$	Gate-Drain Charge			9.2		nC
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_{SD}=-1A$		0.72	1.4	V

**Note:**

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

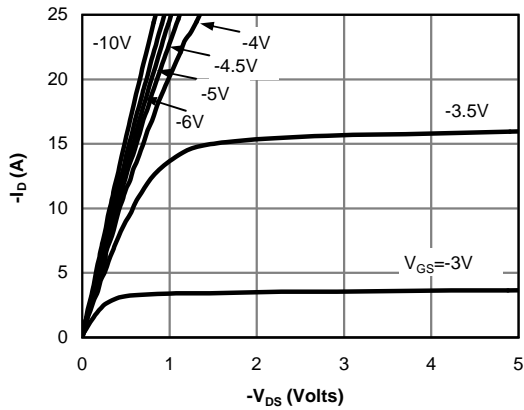


Fig 1: On-Region Characteristics

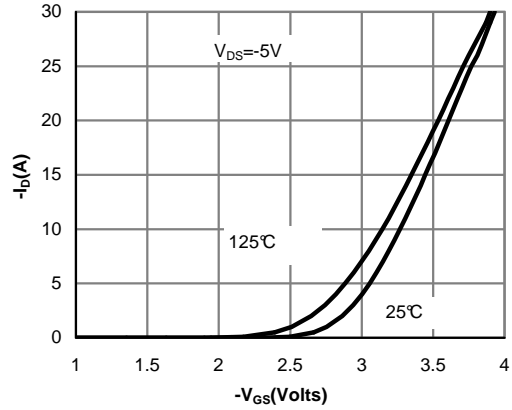


Figure 2: Transfer Characteristics

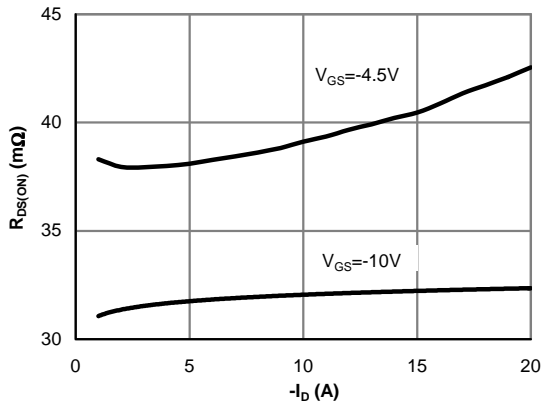


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

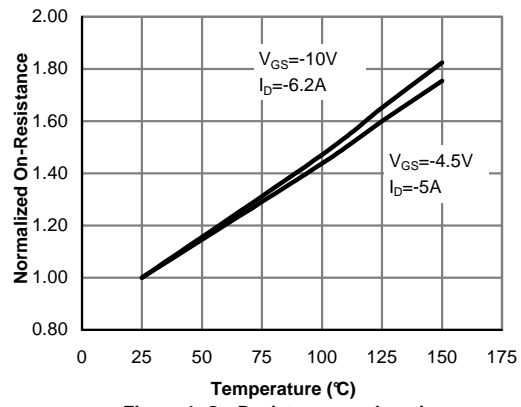


Figure 4: On-Resistance vs. Junction Temperature

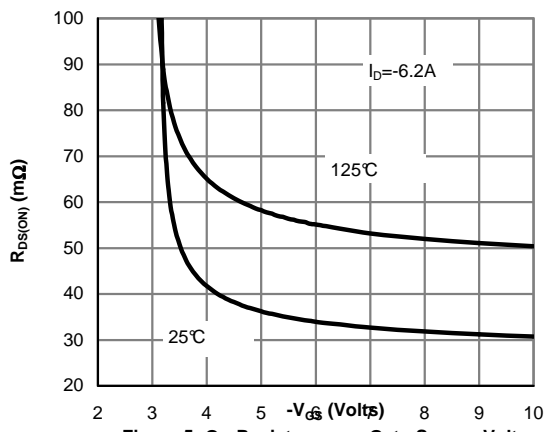


Figure 5: On-Resistance vs. Gate-Source Voltage

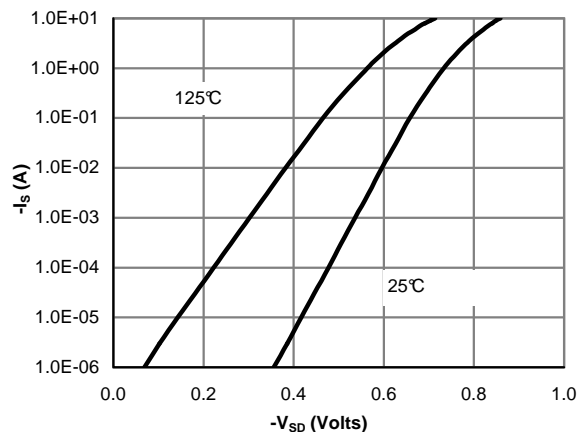


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

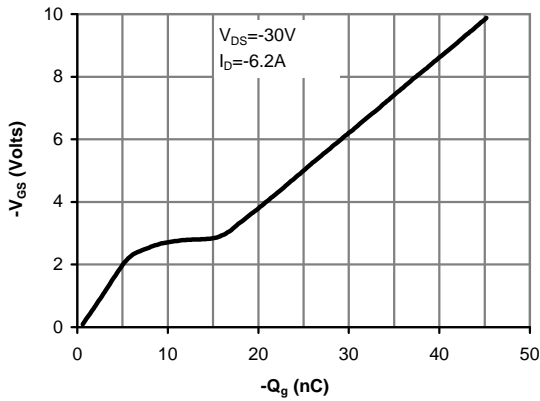


Figure 7: Gate-Charge Characteristics

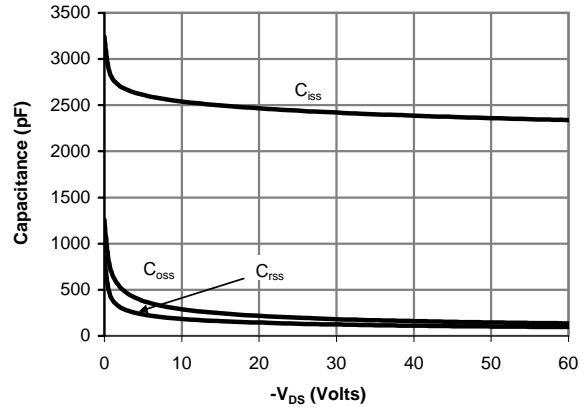


Figure 8: Capacitance Characteristics

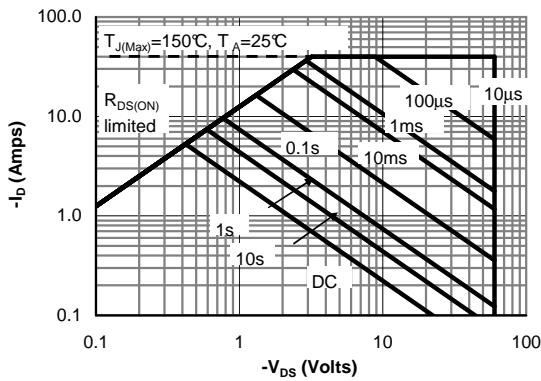


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

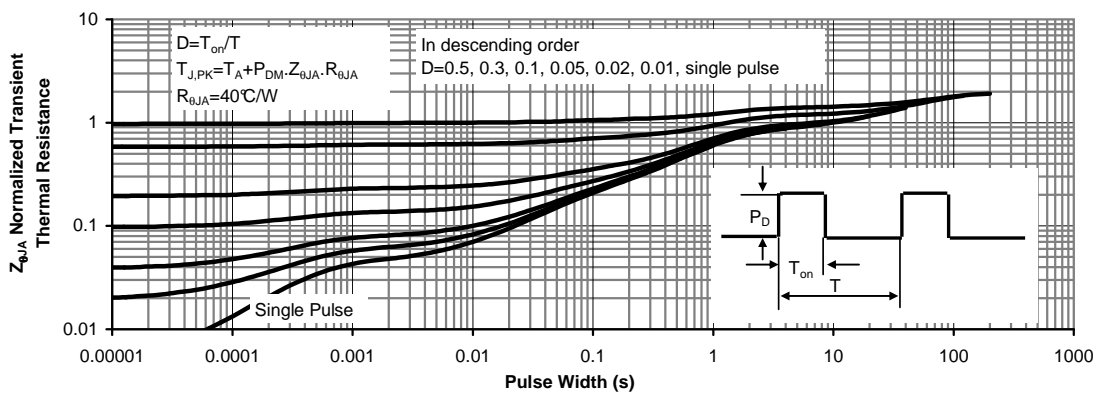
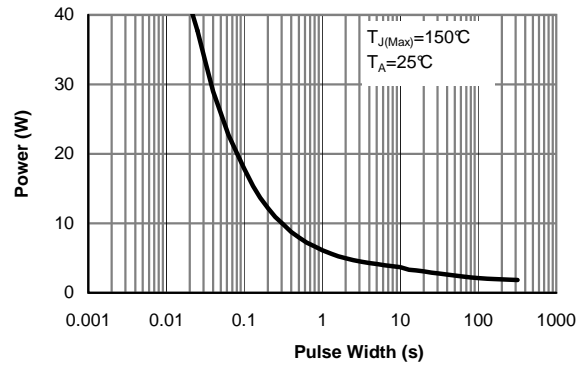
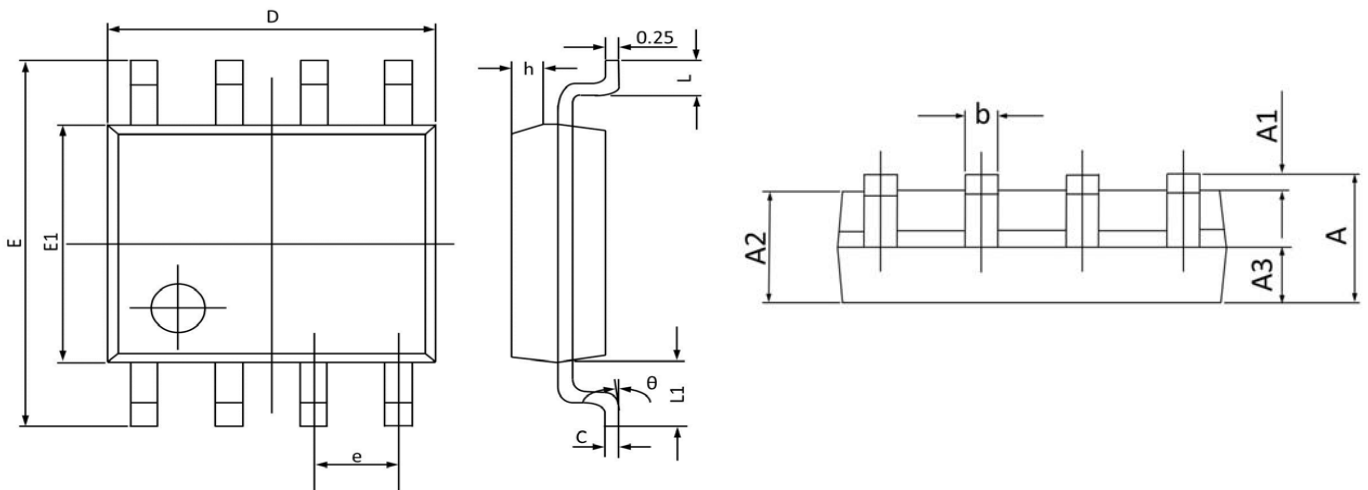


Figure 11: Normalized Maximum Transient Thermal Impedance

## SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.068
A1	0.100	0.250	0.004	0.009
A2	1.300	1.500	0.052	0.059
A3	0.600	0.700	0.024	0.027
b	0.390	0.480	0.016	0.018
c	0.210	0.260	0.009	0.010
D	4.700	5.100	0.186	0.200
E	5.800	6.200	0.229	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.019
L	0.500	0.800	0.019	0.031
L1	1.050(BSC)		0.041(BSC)	
$\theta$	0°	8°	0°	8°